

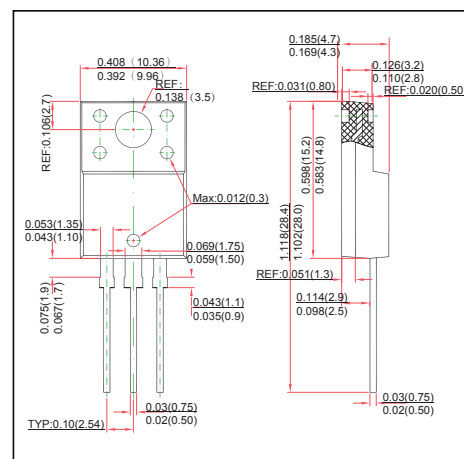
## TO-220F Plastic-Encapsulate MOSFETS

### FEATURE

- High Current Rating
- Lower R<sub>DS(on)</sub>
- Lower Capacitance
- Lower Total Gate Charge
- Tighter VSD Specifications
- Avalanche Energy Specified
- 600V N-Channel Power MOSFET

### MECHANICAL DATA

- Case style: TO-220F moldeplastic
- Mounting position: any



### MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	600	V
Gate-Source Voltage	V <sub>GSS</sub>	±30	
Continuous Drain Current	I <sub>D</sub>	4.0	A
Continuous Drain-Source Diode Forward Current	I <sub>S</sub>	4.0	
Single Pulsed Avalanche Energy (note1)	E <sub>AS</sub>	260	mJ
Thermal Resistance from Junction to Ambient	R <sub>θJA</sub>	62.5	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 ~ +150	°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T <sub>L</sub>	260	

### MOSFET ELECTRICAL CHARACTERISTICS T<sub>A</sub>=25°C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Off characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	600			V
Drain-source diode forward voltage (note2)	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 4.0 A			1.5	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V			25	μA
Gate-body leakage current, forward (note2)	I <sub>GSSF</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = 30 V			100	nA
Gate-body leakage current, reverse (note2)	I <sub>GSSR</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = -30 V			-100	
<b>On characteristics (note2)</b>						
Gate-threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	3.7	4.0	V
Static drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.0 A		2.0	3.0	Ω
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 2 A	2.0	2.6		S
<b>Dynamic characteristics (note3)</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		540	760	pF
Output capacitance	C <sub>oss</sub>			125	180	
Reverse transfer capacitance	C <sub>rss</sub>			8.0	20	
<b>Switching characteristics</b>						
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.0 A		5.0	10	nC
Gate-source charge	Q <sub>gs</sub>			2.7		
Gate-drain charge	Q <sub>gd</sub>			2.0		
Turn-on delay time (note3)	t <sub>d(on)</sub>	V <sub>DD</sub> = 300 V, V <sub>GS</sub> = 10 V, R <sub>G</sub> = 9.1 Ω, I <sub>D</sub> = 4.0 A		12	20	ns
Turn-on rise time (note3)	t <sub>r</sub>			7.0	10	
Turn-off delay time (note3)	t <sub>d(off)</sub>			19	40	
Turn-off fall time (note3)	t <sub>f</sub>			10	20	

#### Notes :

1. L = 30 mH, I<sub>L</sub> = 4 A, V<sub>DD</sub> = 100 V, V<sub>GS</sub> = 10 V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25 °C.
2. Pulse Test : Pulse width ≤ 300 μs, duty cycle ≤ 2%.
3. These parameters have no way to verify.

## RATINGS AND CHARACTERISTIC CURVES

